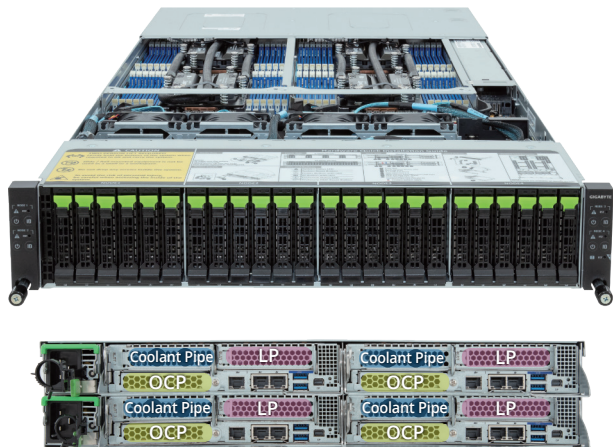


# H273-Z80-LAW1

High Density Server - 2U 4-Node DP 24-Bay NVMe/SATA



## Features

- 2U 4-node rear access liquid cooling solution
- Dual AMD EPYC™ 9005/9004 Series Processors per node
- 12-Channel DDR5 RDIMM, 24 x DIMMs per node
- Dual ROM Architecture
- 8 x 1Gb/s LAN ports via Intel® I350-AM2
- 24x 2.5" Gen4 NVMe/SATA/SAS hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface (optional)
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

## Application

HPC, HCI, Hybrid/Private Cloud Server

## Specification

<b>Dimensions</b>	2U 4-Node - Rear access (W440 x H87.5 x D877 mm)	<b>Power Supply</b>	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
<b>Motherboard</b>	MZ83-HD0	<b>System Management</b>	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
<b>CPU</b>	AMD EPYC™ 9005/9004 Series Processors Dual processor per node, cTDP up to 400W	<b>OS Support</b>	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
<b>Socket</b>	8 x LGA 6096 (Socket SP5)	<b>System Fans</b>	4 x 80x80x38mm (18,300rpm)
<b>Chipset</b>	System on Chip	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Memory</b>	12-Channel DDR5 RDIMM, 96 x DIMMs [EPYC 9005] RDIMM: Up to 6000 MT/s [EPYC 9004] RDIMM: Up to 4800 MT/s	<b>Packaging Co17ntent</b>	1 x H273-Z80-LAW1, 4 x CoolIT CPU cold plate loops, 1 x Mini-DP to D-Sub cable, 1 x 3-Section Rail kit  Packaging Dimensions: w/ cold plate loops: 1185 x 705 x 409 mm w/o cold plate loops: 1176 x 709 x 322 mm
<b>LAN</b>	8 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Support NCSI function 4 x 10/100/1000 management LAN	<b>Part Numbers</b>	Barebone w/ cold plates: 6NH273Z80DR000LCW1* Barebone w/o cold plates: 6NH273Z80DZ000LCW1*  Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - M.2 expansion card - CMTP192: 9CMTTP192NR-00* - GIGABYTE CPU cold plate loop: 25H27-3Z80000-E06X (QPA:4) - GIGABYTE 2U4N manifold: 25H27-3Z80000-E07X (1 set per rack) - Motivair CPU cold plate loop: 25ST7-20000K-M4R (QPA:4) - CoolIT leak sensor board: 6NH273Z80S1000LAN11 (QPA: 4) - RMA packaging: 6NH273Z80SR-RMA-L100
<b>Video</b>	Integrated in ASPEED® AST2600 x 4 (4 x Mini-DP)		
<b>Storage</b>	Front hot-swap: 24 x 2.5" Gen4 NVMe/SATA/SAS *SAS card is required to support SAS drives.  Optional internal M.2: 4 x M.2 (2280/22110)		
<b>RAID</b>	Require RAID add-in cards		
<b>Expansion Slots</b>	4 x LP PCIe Gen5 x16 slots 4 x OCP 3.0 PCIe Gen5 x16 slots		
<b>Rear I/O</b>	8 x USB 3.2 Gen1, 4 x Mini-DP, 8 x RJ45, 4 x MLAN		
<b>Backplane Board</b>	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s		
<b>TPM</b>	4 x TPM headers with SPI interface (Optional TPM2.0 kit: CTM010)		



Learn more at <https://www.GIGABYTE.com/enterprise>

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